Electronic Patent Application Fee Transmittal							
Application Number:	10598514						
Filing Date:	29-Jan-2007						
Title of Invention:	Multiple stacked die window csp package and method of manufacture						
First Named Inventor/Applicant Name:	Chuen Khiang Wang						
Filer:	Linda Johnson Hodge/Elizabeth Whiting						
Attorney Docket Number:	P26634						
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U.S. National Stage under 35 USC 371 Filing	Fees						
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)			
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:				Ţ			
Post-Allowance-and-Post-Issuance:							

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)				
Miscellaneous:								
Submission-Information Disclosure Stmt	1806	1	180	180				
	Tot	180						